Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **T0404-03** DATE: 4/28/2004
Product Affected: IDT82V2082

Date Effective: 7/28/2004

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark "ZB" prefix
- ■ Date Code
- ☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
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Attachment: ■ Yes ☐ No

Samples: Available on request.

DESCRIPTION AND PURPOSE OF CHANGE:
- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ■ Data Sheet
- ■ Other

Please see attachment for detail of change.

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification summary.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

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ATTACHMENT - PCN #: T0404-03

PCN Type: Die Revision and datasheet change

Datasheet Change: Yes

Detail of Change: The new die revision is "ZB", and the definition of pins TERM1 and TERM2 has been changed. This change may affect current customers using the device in Hardware mode, requiring board level changes to use the new "ZB" revision. TERM1/TERM2 pins determine internal/external termination for Rx and Tx. The change will improve the device performance in regards to HPS applications. For a detailed summary of changes including updates to product datasheets, please see URL below:

IDT82V2082 http://www1.idt.com/pcms/getDoc.taf?docID=9660

Devices with the new TERM1/TERM2 pin definition can be identified by the top mark **date code**:

Revision	Date Code Mark
Z (current)	**Z**yyww
ZB (new)	**ZB**yyww

Note: yy = last two digits of the year
ww = workweek

Prior to the PCN effective date of 07/28/04, IDT will ship the current revision (Z) only, unless otherwise requested.

After the PCN effective date of 07/28/04, IDT will ship the new revision (ZB) only, unless otherwise requested. Current customers using the device in hardware mode should evaluate their board design for potential changes that may be required to use the "ZB" revision.

Qualification Data

Qualification Plan: QFI-03-09 **Test Vehicle:** IDT82V2082

Test Description/Condition	Test Methods	Required SS / # Fails	Qual Test Results	
			Lot # 1	Lot # 2
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	77 / 0	77 / 0	77 / 0 [1]
Latch-Up Immunity (+ - I and V stress, + - 100 mA Trigger)	EIA/JESD 78	10 / 0	10 / 0	N/A
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	3 / 0	3 / 0	N/A
ESD Charge Device Model (500V)	JESD22-C101	3 / 0	3 / 0	N/A

Note:

[1] 168 hour Early Life readpoint data. 1000 hour readpoint data expected by May 31, 2004.